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APPL	CATION NO.	FILING DA	ATE	FIRST NAMED INVENTOR		ATTORNEY	DOCKET NO.
	09/38	3,876	08/26/99	RAEDER		С	AMDA.316P
Γ				OWDD / 4556		EXAMINER	
	ROBER	т Ј. (CRAWFORD	QM22/0509	NGUYEN, D		
	CRAWE	ORD PL	LC		ART UNIT	PA	APER NUMBER
	SUITE		AND DRIVE			3723	//
	Ole F	mor ini	00120		DATE MAILED:		05/09/01

Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner of Patents and Trademarks

	Application No.	Applicant/o						
	Application No.	Applicant(s)						
Office Action Summary	09/383,876	RAEDER, CHRISTOPHER H.						
Consequences Cummany	Examiner	Art Unit						
	Dung V Nguyen	3723						
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply								
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136 (a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). - Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b). Status								
1) Responsive to communication(s) filed on	<u> </u>							
2a) ☐ This action is FINAL . 2b) ☑ T	his action is non-final.							
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.								
Disposition of Claims								
4) Claim(s) 1-12 and 14-19 is/are pending in the application.								
4a) Of the above claim(s) is/are withdrawn from consideration.								
5) Claim(s) is/are allowed.								
6)⊠ Claim(s) <u>1-12 and 14-19</u> is/are rejected.								
7) ☐ Claim(s) is/are objected to.								
8) Claims are subject to restriction and/	or election requirement.							
Application Papers								
9)☐ The specification is objected to by the Examiner.								
10) The drawing(s) filed on is/are objected to by the Examiner.								
11)⊠ The proposed drawing correction filed on <u>22 January 2001</u> is: a) approved b)⊠ disapproved.								
12) The oath or declaration is objected to by the Examiner.								
Priority under 35 U.S.C. § 119								
13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).								
a) ☐ All b) ☐ Some * c) ☐ None of:								
1. Certified copies of the priority documents have been received.								
2. Certified copies of the priority documents have been received in Application No								
3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).								
* See the attached detailed Office action for a list of the certified copies not received. 14) Acknowledgement is made of a claim for domestic priority under 35 U.S.C. § 119(e).								
14) Acknowledgement is made of a claim for domestic priority under 35 U.S.C. § 119(e).								
Attachment(s)								
15) Notice of References Cited (PTO-892) 18) Interview Summary (PTO-413) Paper No(s).								
16) Notice of Preferences Cited (PTO-032) 16) Notice of Draftsperson's Patent Drawing Review (PTO-948) 17) Information Disclosure Statement(s) (PTO-1449) Paper No(s	19) Notice of Informa	al Patent Application (PTO-152)						

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DETAILED ACTION

Applicant's request for reconsideration of the finality of the rejection of the last Office action is persuasive and, therefore, the finality of that action is withdrawn.

Drawings

The drawings are objected to as failing to comply with 37 CFR 1.84(p)(5) because they do not include the following reference sign(s) mentioned in the description: 140a, 230 (page 9, line 16-19). Correction is required.

The drawings are objected to under 37 CFR 1.83(a). The drawings must show every feature of the invention specified in the claims. Therefore, the means for positioning the wafer misaligned with respect to the polishing means must be shown or the feature(s) canceled from the claim(s). No new matter should be entered.

Claim Rejections - 35 USC § 112

The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

Claims 1-12 and 14-19 are rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to enable one skilled in the art to which it pertains, or with which it is most nearly connected, to make and/or use the invention. Applicant claims a method for chemical mechanical polishing a wafer comprising a step of determining whether a wafer is being polished in a center-offset manner. What is a standard for determining whether a wafer is being polished in a center-offset manner? What is a thickness at center compare to a

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thickness at an edge of a wafer for considering a wafer is polished in center fast manner? Similarly, what is the difference in thickness of a wafer for considering a wafer is polished in a center slow manner? Applicant also claims an arrangement for chemical-mechanical polishing a wafer comprising a means for determining whether a wafer is polishing in a center-offset manner. What is a device or a component for performing this function? Furthermore, applicant claims a step of positioning or a means for positioning a wafer carrier misaligned with respect to a polishing pad. How does the wafer carrier misalign with the polishing pad? Does it mean an axis of the wafer carrier misaligns with an axis of the polishing pad or an edge of the wafer carrier misaligns with an edge of the polishing pad?

Response to Arguments

Applicant's arguments with respect to claims 1-12 and 14-19 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Dung V Nguyen whose telephone number is 703-305-0036. The examiner can normally be reached on M-F, 6:30-3:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Joseph J Hail can be reached on 703-308-2687. The fax phone numbers for the organization where this application or proceeding is assigned are 703-305-3579 for regular communications and 703-305-3579 for After Final communications.

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Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-1148.

DVN May 8, 2001

Primary Examiner